

HSU83

Silicon Epitaxial Planar Diode for High Voltage Switching

REJ03G0189-0300 Rev.3.00 Feb 16, 2005

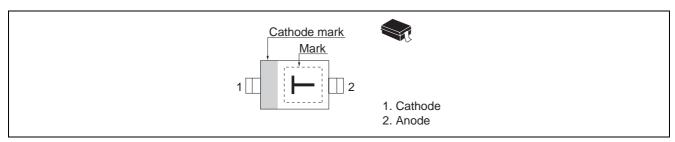
Features

- High reverse voltage. $(V_R = 250 \text{ V})$
- Ultra small Resin Package (URP) is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Renesas Code Previous Code	
HSU83 T		PTSP0002ZA-A	URP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	300	V
Reverse voltage	V _R	250	V
Peak forward current	I _{FM}	300	mA
Non-Repetitive peak forward surge current	I _{FSM} * ¹	2	A
Average rectified current	Io	100	mA
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. Value at duration of 10 ms.

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	1.2	V	I _F = 100 mA
Reverse current	I _{R1}	_	_	0.2	^	V _R = 250 V
	I _{R2}	_	_	100	μΑ	V _R = 300 V
Capacitance	С	_	_	3.0	pF	V _R = 0 V, f = 1 MHz
Reverse recovery time	t _{rr}	_	_	100	ns	$I_F = I_R = 30 \text{ mA}, I_{rr} = 3 \text{ mA}$

Main Characteristics

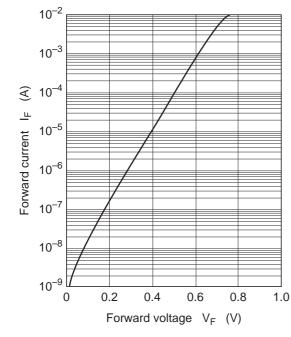


Fig.1 Forward current vs. Forward voltage

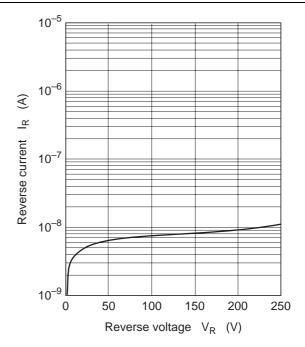
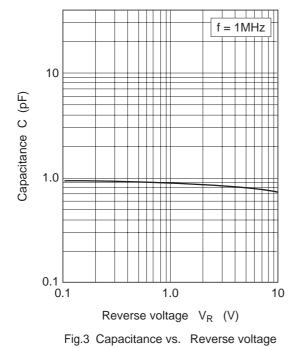
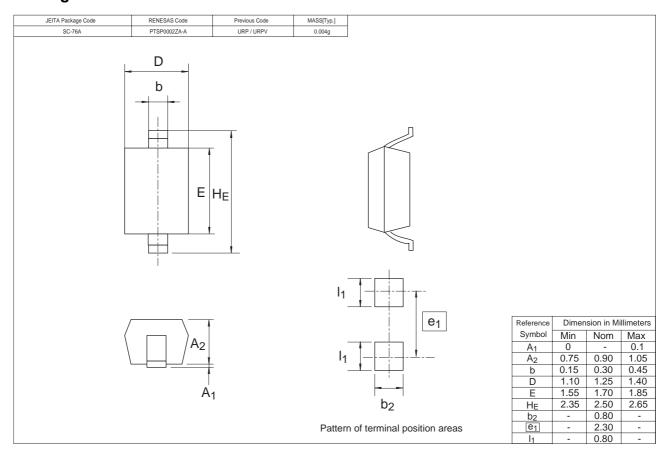


Fig.2 Reverse current vs. Reverse voltage



Package Dimensions



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